High speed optocoupler

XL060L

Thermal Characteristics

	Symbol	Value	Unit
Isolation Voltage	V_{ISO}	3750	Vrms
Operating Temperature	T_{OPR}	-40 ~ +85	°C
Storage Temperature Range	T_{STG}	-55 ~ +125	°C
Soldering Temperature *3	T_{SOL}	260	°C

Notes

1. Pulse width≤1μs, Duty ratio: 0.001
2. 40 to 60% RH, AC for 1 min

Switching Characteristics (@ T_A

Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

Fig. 1 Input Forward Current vs. Forward Voltage

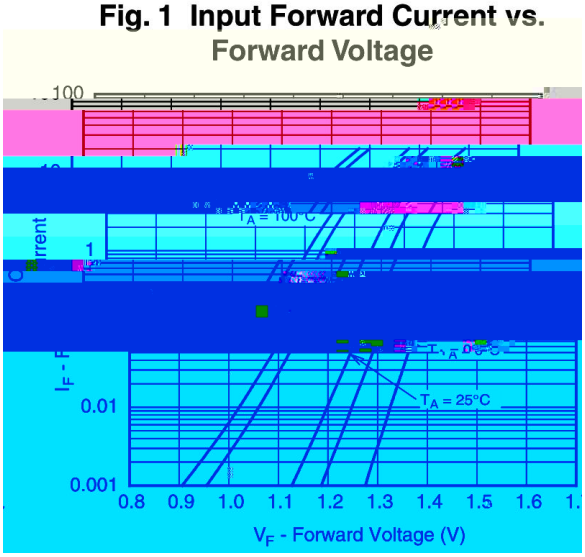


Fig. 2 Input

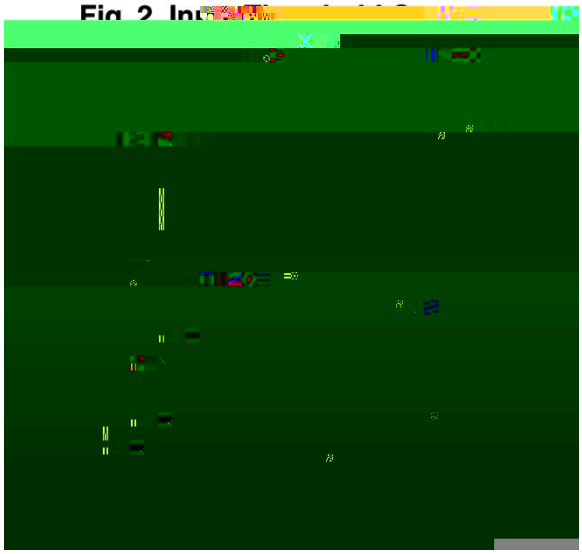


Fig. 3 Low Level Output Voltage vs. Ambient Temperature

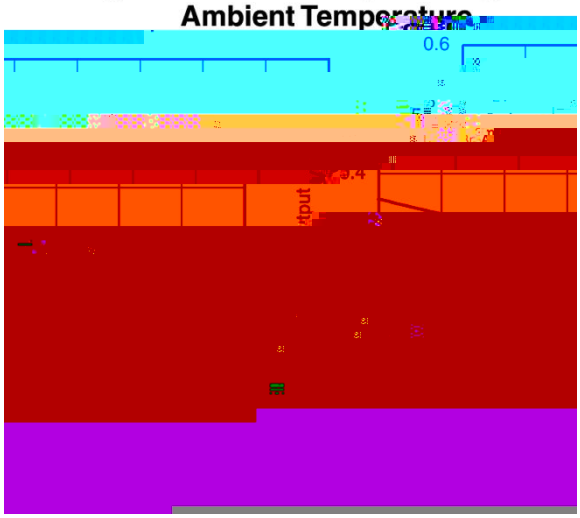


Fig. 4 High Level Output Current vs. Ambient Temperature

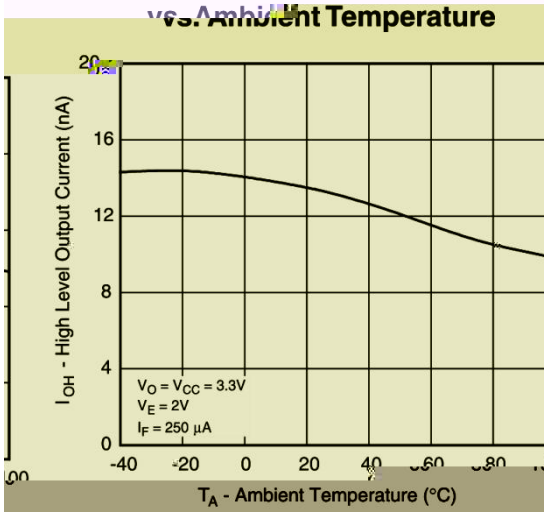


Fig. 5 Low Level Output Current vs. Ambient Temperature

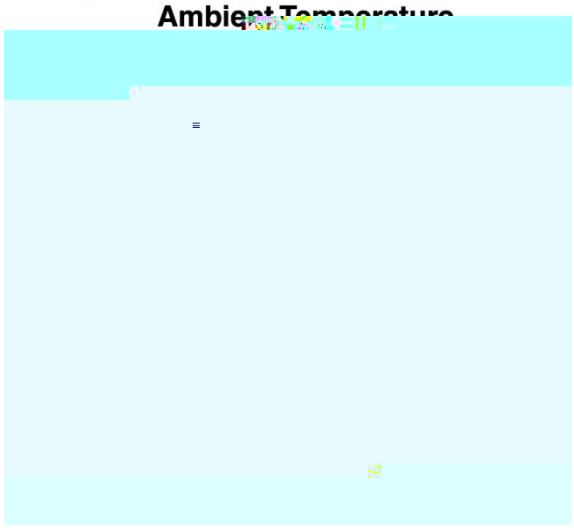
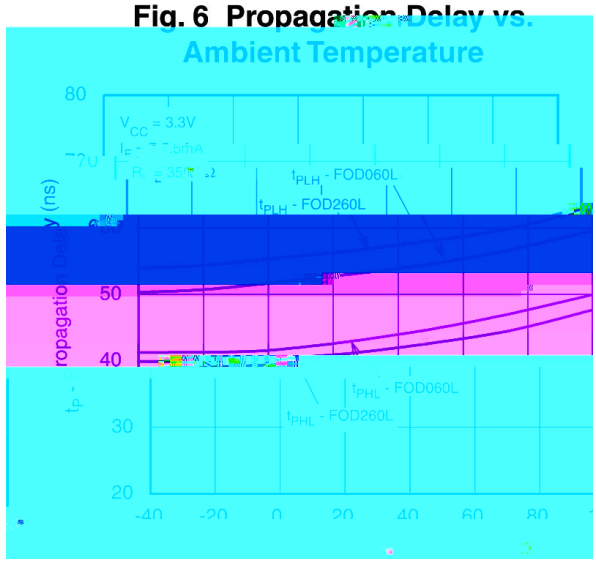


Fig. 6 Propagation Delay vs. Ambient Temperature



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Reflow soldering

	Symbol	Min	Max	Unit
Preheat temperayure	Ts	150	200	
Preheat time	ts	60	120	s
Ramp-up ratea(T_L to T_P)			3	/s
Liquidus temperature	T_L	217		
Time above T_L	t_L	60	150	s
Peak temperature	Tp		260	
Time during which Tc is between (T_P-5) and T_P	t_p		30	s
Ramp-down rate(T_P to T_L)			6	/s

Note:
Reflow soldering is recommended at the temperatures and times shown, no more than three times.

Wave soldering

Profile feature
Average ramp-up

Soldering with hand soldering iron

A. Hand soldering iron is only used for product rework or sample testing.

B. Hand soldering iron requirements:Temperature:360 +5 within 3s.

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XL060L ?